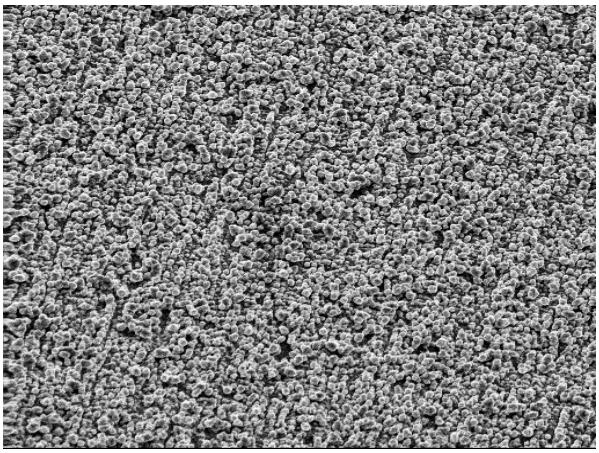
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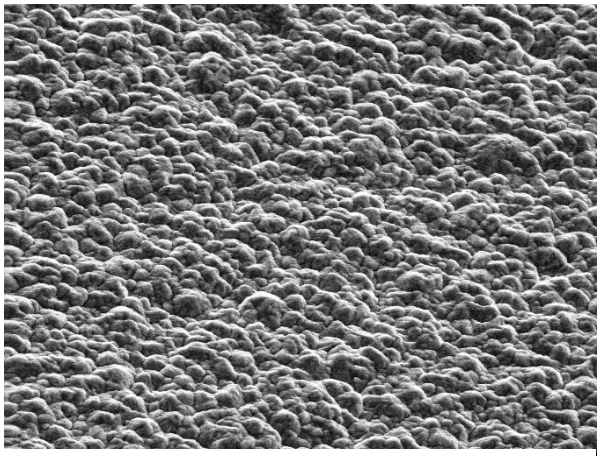
Performance Copper Foils

MLS TOC-500

MLS TOC500 is a reverse treated, zinc free copper foil designed for applications on PTFE (Teflon™) and other fluorocarbon resin-based, high frequency laminates .



Treated (Drum) Side MLS TOC-500 (1/2 Ounce)



Matte Side MLS TOC-500 (1/2 Ounce)

Nominal Thickness		microns	18	35	70
Area Weight		oz/ft²	1/2	1	2
Tensile	Ambient	Kpsi	60	55	52.5
	180° C	Kpsi	30	30	30
Elongation	Ambient	%E	8	15	20
	180° C	%E	8	8	8
Roughness - Rz	Drum Side	µinch	120	120	120
Roughness - Rz	Matte Side	µinch	200	225	350
Peel Strength PTFE	Drum Side	Lbs/in	12.5	15.0	18.0

Performance Benefits

- VLP bonding surface, minimal foil treatment residue after etching.
- Superior etch factor for fine lines.
- Reduced costs through process step elimination during PCB fabrication.
- HTE characteristics eliminate inner foil cracking

***Note**: Nominal thickness is determined by area weight. Actual measured thickness may be slightly higher due to matte side topography.

The information contained in this data sheet is not intended to and does not create any warranties, express or implied, including any warranty of merchantability or fitness for a particular purpose. The actual performance of Mitsui materials will vary according to the customer's application.